

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

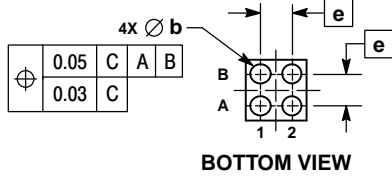
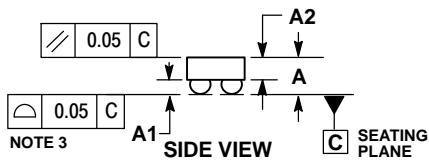
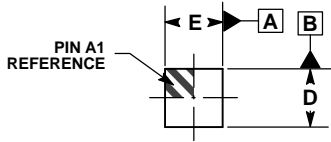
ON Semiconductor®



  
SCALE 4:1

WLCSP4, 0.64x0.64  
CASE 567KA  
ISSUE A

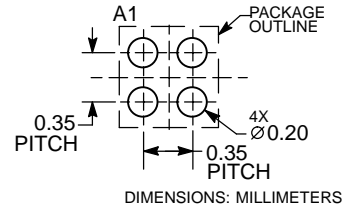
DATE 03 AUG 2016



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.35	0.40	0.45
A1	0.14	0.16	0.18
A2	0.25 REF		
b	0.185	0.200	0.215
D	0.610	0.640	0.670
E	0.610	0.640	0.670
e	0.35 BSC		

### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WLCSP4, 0.64X0.64	PAGE 1 OF 2

